

产品编号 (Item No) : NYHP-7003C

型号 (Model) : NYHP-7003C

High Frequency Very Low Loss Laminate

**特点:**

- 低介电常数(Dk 3.38@10 GHz)
- 介质损耗(Df 0.0030@10 GHz)
- Tg>200℃无铅兼容板材
- 优异通孔可靠性及 PCB 加工性
- 低吸水性

**应用领域:**

- 天线
- 微波/无线通讯

**FEATURES:**

- Low Dk (Dk 3.38@10 GHz)
- Low Df (Df 0.0030@10 GHz)
- Tg>200°C, Lead-free compatible
- Superior PTH reliability and easy PCB processing
- Low moisture absorption

**APPLICATIONS:**

- Antenna
- Microwave/Wireless Communication

**NYHP-7003C 基板产品规格表 Specification Sheet for Laminate**

NYHP-7003C 覆铜板 NYHP-7003C Type Laminate	单位Units Metric(English)	典型值 Typical Value 1.524mm CCL	条件 Condition	测试方法 Test Method IPC TM 650
1. 抗剥强度 Peel Strength, As received	N/mm(lb/inch),	>1.0 (5.7)	1oz HTE	2.4.8
2. 体积电阻 Volume Resistivity,	MΩ-cm, Minimum	1.8×10 <sup>10</sup>	COND A	2.5.17.1
3. 表面电阻 Surface Resistivity,	MΩ, Minimum	4.3×10 <sup>9</sup>	COND A	2.5.17.1
4. 吸水率 Moisture Absorption	% maximum	0.06		2.6.2.1
5. 介电常数 Permittivity (Laminate & Prepreg as laminated)	--- maximum	3.38	10 GHz/23℃	2.5.5.5
6. 介质损耗 Loss Tangent (Laminate & Prepreg as laminated)	--- maximum	0.0030	10 GHz/23℃	2.5.5.5
7. TCDK	PPM/℃	48	-50℃-150℃	2.5.5.5
8. 弯曲强度 Flexural Strength, A. 纵向 Length direction B. 横向 Cross direction	N/mm <sup>2</sup> , minimum	220 140	RT	2.4.4
9. 热应力冲击 Thermal Stress A. 未蚀刻 Unetched B. 蚀刻 Etched	10 sec at 288℃	Pass Pass	288℃	2.4.13.1
10. 燃烧性 Flammability (Laminate & Prepreg as laminated)	rating	V-0		UL94 (UL File: E213990)
11. 玻璃态转化温度 Glass Transition Temperature	℃	>200	DMA	2.4.24
12. 热分解温度 Decomposition Temperature	℃	400		TD (5% wt loss)
13. 膨胀系数 Z-CTE A. 50 to 280 ℃	PPM/℃	50		2.4.24
14. 耐热性(除去铜箔) Thermal Resistance (Copper removed) A.T260 B.T288 C.T300	Minutes Minutes Minutes	>120 > 60 > 60		2.4.24.1
15. 耐CAF性能 CAF Resistance	Pass/Fail	Pass	AABUS	2.6.25
16. 导热系数 Thermal Conductivity	W/m•℃	0.69		ASTM D5470

\*AABUS = 供需双方商定 As agreed upon between user and supplier.